



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abbott

Art Unit: 2826

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Serial No.: 09/525,105

Examiner: Williams, A.

Filed: 03/14/00

Docket: TI-28098

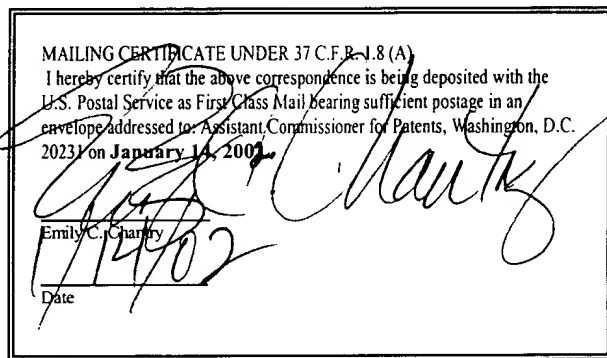
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2/14/02

For: **GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR DEVICES
AND METHOD OF FABRICATION**

AMENDMENT 37 CFR 1.115

January 14, 2002

Assistant Commissioner
for Patents
Washington, D.C. 20231



Sir:

Responsive to the Office Action of September 20, 2001, please amend the application as follows:

Claim 1. (Amended) A leadframe for use with packaged integrated circuit chips comprising:
a plated layer of gold selectively covering [outer areas]
segments of said leadframe external to said package,
intended for solder attachment.

Claims 2. (Amended) A leadframe for use with packaged integrated circuit chips, having a chip mount pad and a plurality of lead segments, comprising: